

# intel® Technical Advisory

TA-561-1

5200 NE Elam Young Parkway  
Hillsboro, OR 97124

May 22, 2002

## CDROM Drive "Door Sticking", corrected with Manufacturing Deviation

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### Products Affected

All TSRMT2 Carrier/Industrial Grade Server products:  
TMA0100  
TMD0100

### Description

When attempting to open the CDROM door, it may become stuck causing it to not open or not fully open under its' own power. In the worst case, the door would appear to remain latched, but if you gently pry at the door, it will pop open. In other cases the door will open, just not fully.

The hardware configuration that is susceptible to this issue is the Mullins chassis, with Mitsumi CDROM and the EMI shield (PNs A70866-003, A70866-002).

This issue was discovered at the Intel factory during the initial 69 unit rework for HP (39 of the units were Mullins, 3 of which exhibited this problem). The 39 Mullins systems (with A70866-002 EMI shield) were functionally tested for this issue before they were shipped to HP. This issue has not been reported to Intel by any customer.

### Root Cause

The assembled system has insufficient margin between the top flange of the chassis's' media bay and the top cover of the CDROM.

There are two components contributing to the root cause of this issue:

- The Mitsumi CDROM has less ejection force than Teac drives.
- Upper EMI shield (PNs A70866-003, A70866-002) has spring fingers that are too stiff for the gap resulting in excessive force/deflection on the top of the CDROM.

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## Resolution

There are two component changes comprising resolution to this issue:

- TSRMT2 systems will be manufactured with Teac CDRROM drives. This change is being implemented immediately via a Manufacturing Deviation, and will be ECO'ed into the product.
- The EMI shield design has been modified in two ways: an emboss was added to give the span of the EMI shield stiffness to resist spring force, and spring geometry was changed to reduce the force on the top cover of the CDRROM. The part number of modified EMI shield design has rolled to A70866-004. The -004 shield has been implemented immediately via a Manufacture Deviation, and will be ECO'ed into the product.



EMI Shield Front Corners  
(Pictured Left: -004) (Pictured Right: -003)

### TMA0100 & TMD0100 received by HP from Intel:

The 39 Mullins systems (with A70866-002 EMI shield) were functionally tested for this issue before they were shipped to HP. There is no action required for these systems.

All future shipments of TSRMT2 systems will be manufactured to include the changes listed in the *Resolution* section of this document. There is no action required for these systems.

### FRU stock purchased by HP from Foxconn:

When ordering parts and stock from Foxconn make certain any assembly or subassembly that includes the correct version of the EMI shield (A70866-004 EMI shield).

Hard-tooled parts (A70866-004 EMI shield) are scheduled to become available through Foxconn on the week of July 1, 2002. If stock is required from Foxconn prior to 07/01 then Intel will work with Foxconn to fill the order.

Please contact your Intel Sales Representative if you require more specific information about this issue.

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